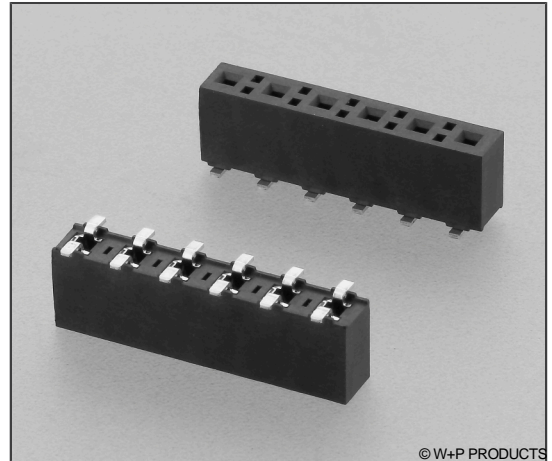


46-3950 Economy Version

SMT-Buchsenleisten RM 5,08mm, stehend – Power-Kontakte, durchsteckbar
SMT Female Headers, 5.08mm Pitch, Vertical – Power Contacts, Pass Through

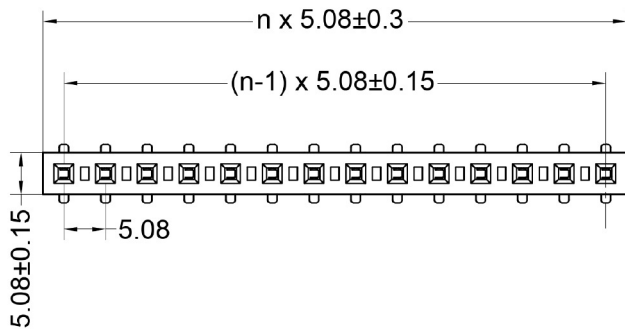
Technische Daten / Technical Data

| | |
|--|--|
| Isolierkörper <i>Insulator</i> | Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i> |
| Kontaktmaterial <i>Contact Material</i> | Kupferlegierung <i>Copper alloy</i> |
| Kontaktoberfläche <i>Contact Surface</i> | Lt. Oberflächenoptionen, über Ni <i>Acc. to plating options, over Ni</i> |
| Durchgangswiderstand <i>Contact Resistance</i> | < 20 mΩ |
| Isolationswiderstand <i>Insulation Resistance</i> | > 1000 MΩ |
| Spannungsfestigkeit <i>Test Voltage</i> | 1000 V AC/DC |
| Nennstrom <i>Current Rating</i> | 7 A |
| Temperaturbereich <i>Temperature Range</i> | -40 °C ~ +105 °C |
| Verarbeitung <i>Processing</i> | 260 °C für 10 sec. / 230 °C für 30–60 sec. 260 °C for 10 sec. / 230 °C for 30–60 sec. |

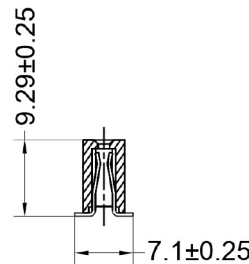
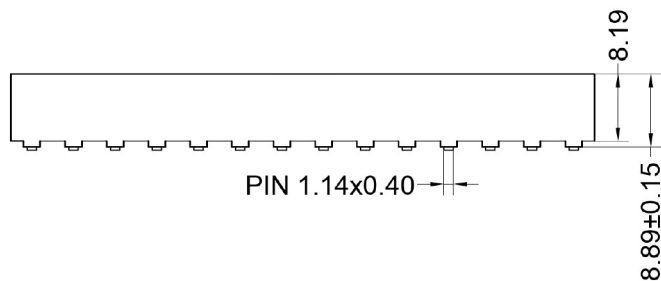
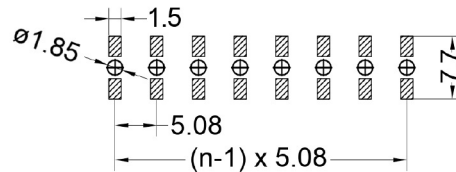


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Geeignet für 1,14mm Vierkantstifte
Mates with 1.14mm square pins



Recommended P.C.B Layout (Top Side)
(PCB BOARD TOLERANCE ±0.05)



| | | | | |
|----------------|--------------------|---|--|---------------------------------|
| Series | Contacts* | Plating* | Locating Pegs | Packaging* |
| 46-3950 | 14 02-20 | 00 00 Vergoldet Gold plated 50 Verzinkt Tin plated | 00 00 Ohne Pos.hilfen W/o loc. pegs | ST ST PPST PPTR |

Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads
PPST In Stangen mit P&P-Pads / In tubes with P&P-Pads
PPTR Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** - please replace by your specifications.

Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

| Profileigenschaft | Kennwert |
|--------------------------------------|---------------------------------|
| Temperatur Minimum T_{Smin} | 150 °C |
| Temperatur Maximum T_{Smax} | 200 °C |
| Dauer $T_{Smin} - T_{Smax}$ | 60 – 180s |
| Temperatur Lötbereich T_L | untere Temperaturangabe [°C] |
| Verweildauer oberhalb T_L | laut Angabe im Datenblatt [sec] |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3 °C / s |
| Höchsttemperatur T_P | obere Temperaturangabe [°C] |
| Dauer Höchsttemperatur | laut Angabe im Datenblatt [sec] |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6 °C / s |
| Dauer 25 °C – Höchsttemperatur T_P | max. 8m |

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

| Profile Feature | Key Values |
|--------------------------------------|-------------------------|
| Minimum Temperature T_{Smin} | 150 °C |
| Maximum Temperatur T_{Smax} | 200 °C |
| Duration $T_{Smin} - T_{Smax}$ | 60 – 180s |
| Soldering Range Temperature T_L | Lower Temperature [°C] |
| Duration above T_L | Acc. to datasheet [sec] |
| Ramp-Up Rate $T_{Smax} - T_P$ | max. 3 °C / s |
| Peak Temperature T_P | Upper Temperature [°C] |
| Duration Peak Temperature | Acc. to datasheet [sec] |
| Ramp-Down Rate $T_{Pmax} - T_{Smin}$ | 6 °C / s |
| Duration 25°C - Peak Temp. T_P | max. 8min |

